

Serial No. 09/875,659  
August 18, 2003  
Reply to the Office Action dated March 19, 2003  
Page 2 of 6

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claim 1 (original): A method for producing an electronic part having a plurality of internal electrodes, said method comprising:

laminating a plurality of ceramic green sheets one on top of the other, at least some of the ceramic green sheets having conductive paste on a surface thereof such that the conductive paste is located between two adjacent ceramic green sheets,

baking the laminated product to obtain the electronic part, the contraction ratio of the ceramic material forming the ceramic green sheet being greater than the contraction ratio of the conductive paste.

Claim 2 (new): The method to claim 1, wherein a lateral edge of at least one of the internal electrodes has a wedge-like cross-sectional shape and the length L of the wedge and the thickness t of the internal electrode at the base of the wedge satisfies the relationship  $L > 2t$ .

Claim 3 (new): The method according to claim 1, wherein the thickness of each of the internal electrodes is in the range of about 3  $\mu\text{m}$  to about 20  $\mu\text{m}$ .

Claim 4 (new): The method according to claim 1, wherein the conductive paste has a low ratio of a binder to be scattered after baking and a high ratio of metal powders.

Claim 5 (new): The method according to claim 4, wherein the conductive paste

Serial No. 09/875,659

August 18, 2003

Reply to the Office Action dated March 19, 2003

Page 3 of 6

has about 2% to about 5% by weight of the binder with respect to 100% by weight of the metal powders.

**Claim 6 (new):** The method according to claim 1, wherein the conductive paste includes a high melting point metal.

**Claim 7 (new):** The method according to claim 6, wherein the high melting point metal is at least one metal selected from the group consisting of Ni, Mo, and W.